

Title (en)
Lead-free, free-cutting copper alloys

Title (de)
Bleifreie Automatenkupferlegierung

Title (fr)
Alliage de cuivre de décolletage sans plomb

Publication
EP 1600516 A2 20051130 (EN)

Application
EP 05017190 A 19981116

Priority
• EP 98953071 A 19981116
• JP 28859098 A 19981012

Abstract (en)
The present invention relates to lead free, free cutting copper alloys and methods of their manufacture. In particular, the present invention is directed to a lead-free, free-cutting copper alloy which comprises 70 to 80 percent, by weight, of copper; 1.8 to 3.5 percent, by weight, of silicon; and at least one element selected from among 0.3 to 3.5 percent, by weight, of tin, 1.0 to 3.5 percent, by weight, of aluminium, and 0.02 to 0.25 percent, by weight, of phosphorous; and the remaining percent, by weight, of zinc and wherein the metal structure of the free cutting copper alloy has at least one phase selected from the gamma (gamma) phase and the kappa (kappa) phase. <IMAGE>

IPC 1-7
C22C 9/04; **C22F 1/08**

IPC 8 full level
C22F 1/00 (2006.01); **C22C 9/04** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP KR)
C22C 9/04 (2013.01 - EP KR); **C22F 1/08** (2013.01 - EP)

Cited by
EP2960350A1; EP3985136A1; DE102020127317A1

Designated contracting state (EPC)
BE DE FI FR GB IT SE

DOCDB simple family (publication)
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